<b>SPEC</b>	IFI	CAT		NS
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SAMPLE CODE · SH240320T-063-L-Q

MASS PRODUCTION CODE . PH240320T-063-L-Q

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 001

DRAWING NO. (Ver.) . LMD-PH240320T-063-L-Q (Ver:001)

PACKAGING NO. (Ver.)

# **Customer Approved**

Date:

Approved	Checked	Designer
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2012.08.06

TW RD APR

- Preliminary specification for design input
- Specification for sample approval

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# **History of Version**

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
2012/08/06	01	001	New Drawing	-	Yuan
				<b>~</b>	
		5			

Total: 25 Page



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Note: For detailed information please refer to IC data sheet:

Primacy(TFT LCD): ILITEK: ILI9341



#### 1. SPECIFICATIONS

### 1.1 Features

### Main LCD panel

Item	Standard Value
Display Type	240(R · G · B) * 320 Dots
LCD Type	Normally white , Transmissive type
Screen size(inch)	2.8 inch
Viewing Direction	12 O'clock
Color configuration	RGB-Strip
Backlight	LED Backlight
Interface	8/16-bit 80-system I/F
Other(controller/driver IC)	ILITEK: ILI9341
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer web side :
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/

# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	50.0(W) * 69.2 (L) * 3.4 (H)	mm

## LCD panel

Item	Standard Value	Unit
Active Area	43.2 (W) * 57.6 (L)	mm



## 1.3 Absolute Maximum Ratings

#### Module

Item	Symbol Condition		Min.	Max.	Unit
Custom Davier County Valtage	VCC -		-0.3	+4.6	V
System Power Supply Voltage	VGH ~ VGL	-	-0.3	+32	V
Input Voltage	VIN	-	-0.3	VCC+0.3	V
Operating Temperature	$T_OP$	-	-20	+70	°C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	°C
Storage Humidity	$H_D$	Ta 40 °C	20	90	%RH

#### 1.4 DC Electrical Characteristics

Module GND = 0V, Ta = 25°C

					,	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage1	VCC	-	-	2.8	-	V
Input High Voltage	V <sub>IH</sub>	-	0.7 VCC	-	VCC	V
Input Low Voltage	V <sub>IL</sub>	-	GND	-	0.3 VCC	V
Output High Voltage	V <sub>OH</sub>	IOH=-0.1mA	0.8*VDD	-	VDD	V
Output Low Voltage	V <sub>OL</sub>	IOL=0.1mA	GND	-	0.2*VDD	V
Supply Current	ICC	VCC = 2.8V Pattern=full display *1	1	TBD	TBD	mA

Note1:Maximum current display



## 1.5 Optical Characteristics

#### **TFT LCD Module**

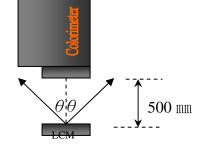
VCC = 2.8V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	unit	-
Response tim	ne	Tr+ Tf	Ta = 25°C θX, θY = 0°	-	TBD		ms	Note2
	Тор	θΥ+		-	TBD	-		
Viewing angle	Bottom	θΥ-	CR ≥ 10	-	TBD	-	Dog	Note4
viewing angle	Left	θX-	CR 2 10	-	TBD	-	Deg.	NOIE4
	Right	θX+		-	TBD	-		
Contrast rati	0	CR	Ta = $25^{\circ}$ C $\theta$ X , $\theta$ Y = $0^{\circ}$	200	250	-	1	Note3
	White	Х		TBD	TBD	TBD		
	vville	Y		TBD	TBD	TBD		
0 1 6015	Red	Х		TBD	TBD	TBD		
Color of CIE Coordinate	Reu	Υ		TBD	TBD	TBD		
(With B/L&T/P)	Green	Χ	-	TBD	TBD	TBD	_	
(With Breath )	Green	Υ		TBD	TBD	TBD		
	Blue	X		TBD	TBD	TBD		Note1
	Diue	Υ		TBD	TBD	TBD		
Average Brightr	ness							
Pattern=white display		IV	IF=80 mA	TBD	TBD	-	cd/m <sup>2</sup>	
(With B/L&T/P) *1								
Uniformity (With B/L&T/P	)*2	△B	IF=80 mA	70	-	-	%	

#### Note 1:

- \*1 : △B=B(min) / B(max) \* 100%
- \*2 : Measurement Condition for Optical Characteristics:
  - a: Environment: 25 ±5 / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance:  $500 \pm 50$  mm  $\rightarrow (\theta = 0^{\circ})$
  - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





Colorimeter=BM-7 fast

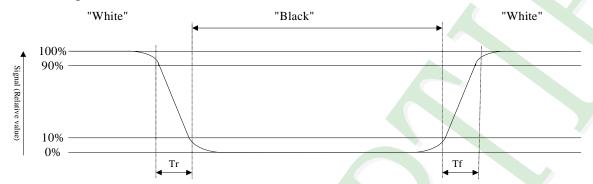
To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)



#### Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

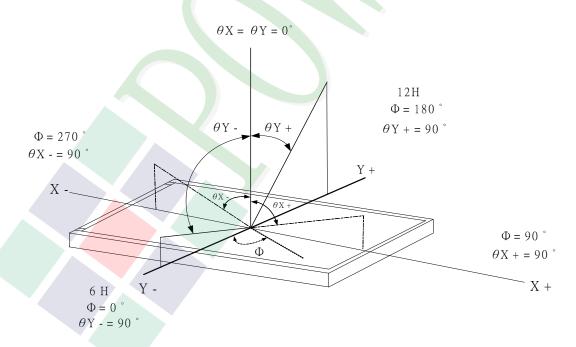
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





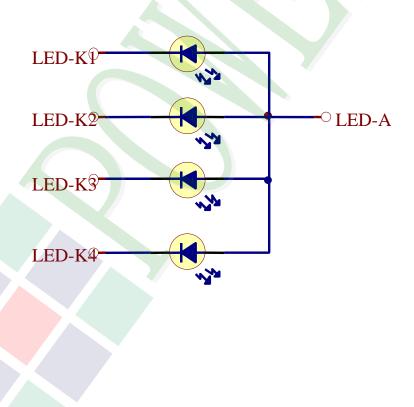
# 1.6 Backlight Characteristics

**Maximum Ratings** 

Item	Symbol	Conditions	Min.	Max.	Unit
Power Dissipation	PD	Ta =25°ℂ	_	TBD	W

**Electrical / Optical Characteristics** 

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF			TBD	TBD	V
Average Brightness (without LCD)	IV	IF= 80 mA	TBD	TBD	-	cd/m <sup>2</sup>
CIE Color Coordinate	Х		TBD	TBD	TBD	
(Without LCD)	Y		TBD	TBD	TBD	1
Color			White			



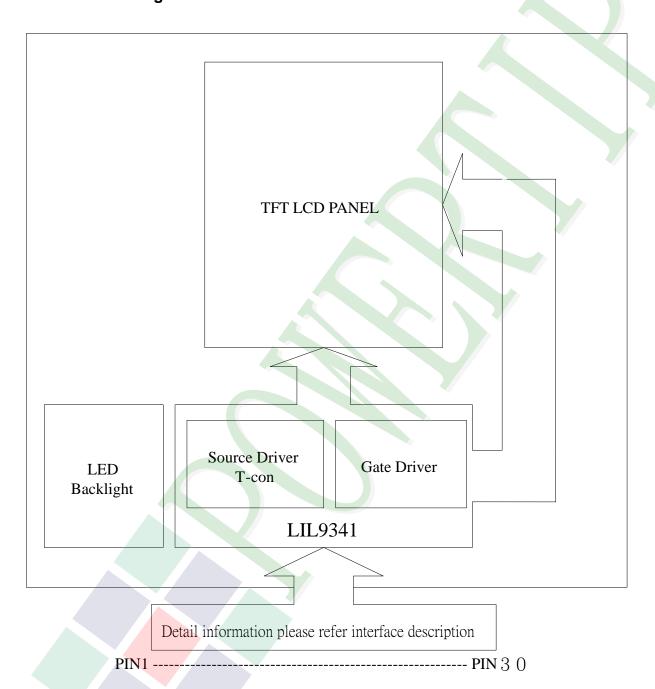


## 2.1 Counter Drawing

### 2.1.1 LCM Mechanical Diagram

\* See Appendix

## 2.1.2 Block Diagram





# 2.2 Interface Pin Description

Pin No.	Symbol	Function
1	LEDK1-4	Power supply for LED Backlight Cathode input
2	LEDA	Power supply for LED Backlight Anode input
3	GND	Signal ground.(0V)
4	RESET	Reset input pin for TFT LCD.  When RESET is "L", initialization is executed.
5	DB17	
6	DB16	
7	DB15	
8	DB14	
9	DB13	
10	DB12	
11	DB11	
12	DB10	Bi-directional data bus
13	DB8	Di-directional data bus
14	DB7	
15	DB6	
16	DB5	
17	DB4	
18	DB3	
19	DB2	
20	DB1	
21	RD	Read signal input , active at Low.
22	WR/SCL	Write signal input , active at Low.
23	RS	When RS = 0: Command. When RS = 1: Display data.
24	CS	Chip select signal , Active at "L"
25	XR/X+	NC

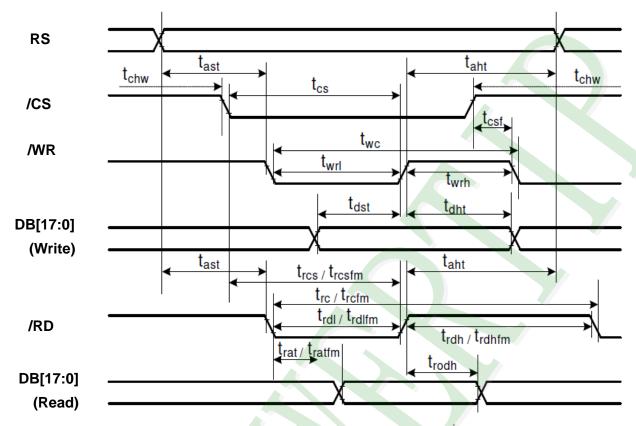


Pin No.	Symbol	Function
26	YD/Y-	
27	XL/X-	NC
28	YU/Y+	
29	GND	Signal ground.(0V)
30	2.8 /VCC	Power supply for the internal logic circuit.





## 2.3 Timing Characteristics

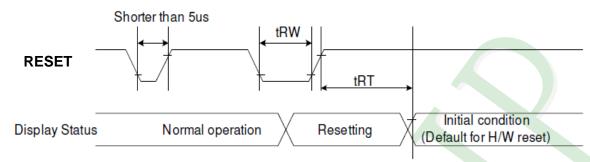


Signal	Symbol	Parameter	min	max	Unit	Description
Be	tast	Address setup time	0		ns	
RS	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
/cs	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
/WR	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
/RD(FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
/RD(ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
DB[47.0]	tdst	Write data setup time	10	-	ns	
DB[17:0] DB[17:0]	tdht	Write data hold time	10	-	ns	For maximum CL=30pF
DB[8:0]	trat	Read access time	-	40	ns	For minimum CL=8pF
DB[7:0]	tratfm	Read access time	-	340	ns	TOT MINIMUM OL=OPE
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70  $^{\circ}$ C, VCC=1.65V to 3.3V, VCI=2.5V to 3.3V, GND=0V



#### **Reset Timing**



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10	7	uS
	tRT	Reset cancel		5 (note 1,5)	mS
	thi	neset cancer		120 (note 1,6,7)	mS

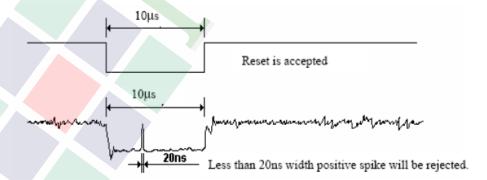
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



- Note 5: When Reset applied during Sleep In Mode.
- Note 6: When Reset applied during Sleep Out Mode.
- Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



### 2.4 Reference Initial code

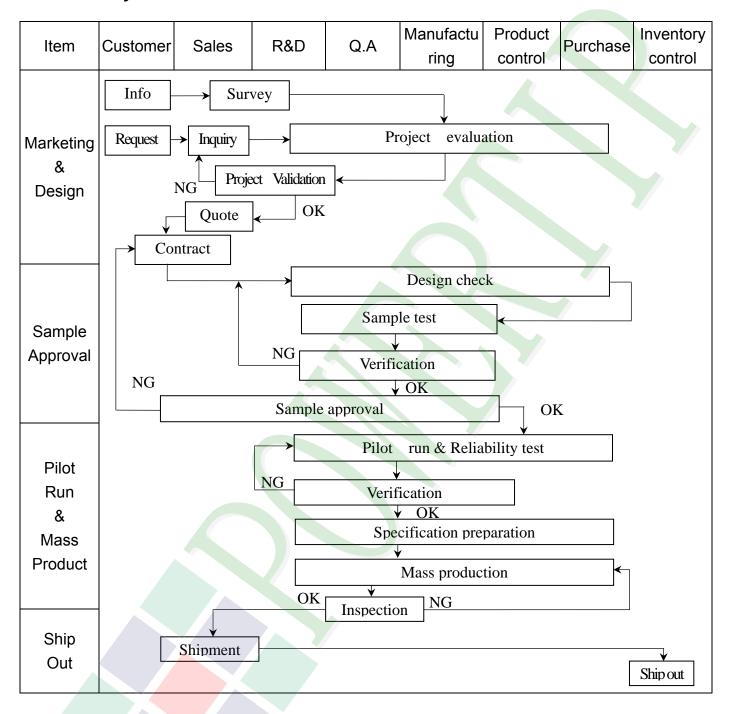
**TBD** 



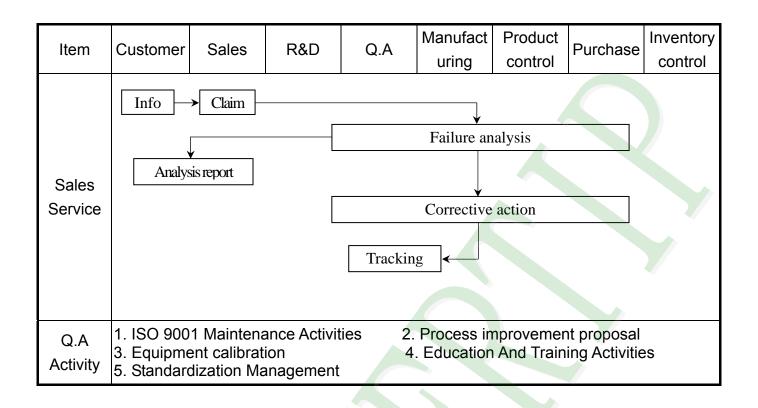


#### 3. QUALITY ASSURANCE SYSTEM

### 3.1 Quality Assurance Flow Chart









## 3.2 Inspection Specification

◆Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).

◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment: Gauge、MIL-STD、Powertip Tester、Sample

◆Defect Level: Major Defect AQL: 0, 4 ; Minor Defect AQL: 1, 5

◆OUT Going Defect Level: Sampling.

◆Standard of the product appearance test:

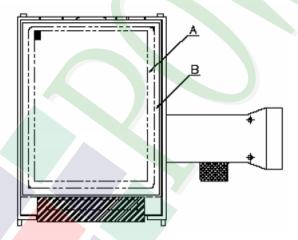
a. Manner of appearance test:

(1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area : viewing area

B area : Outside of viewing area

(4). Standard of inspection: (Unit: mm)



## ◆Specification For TFT-LCD Module Less Than 3, 5":

NO	Item		Criterion				
			1. 1The part number is inconsistent with work order of production.			Major	
01	Product condition	1. 2 Mi	1. 2 Mixed product types.				
		1. 3 Ass	sembled	in inverse direction.		Major	
02	Quantity	2. 1The	e quantit	y is inconsistent witl	h work order of production.	Major	
03	Outline dimension		3. 1 Product dimension and structure must conform to structure diagram.				
		4. 1 Mi	issing line	e character and icon		Major	
		4, 2 No function or no display.					
04	Electrical Testing	4. 3 Display malfunction.					
		4. 4 LCD viewing angle defect.				Major	
		4. 5 Cu	irrent co	nsumption exceeds p	product specifications.	Major	
				Item	Acceptance (Q'ty)		
	Dot defect			Bright Dot	≦ 2		
			Dot	Dark Dot	≦ 3		
0.5	(Bright dot \		Defect	Joint Dot	≦ 2		
05	Dark dot)			Total	≦ 3	Minor	
	On -display	5. 1 Ins	spection	pattern: full white	, full black , Red , Green and		
		blue screens.					
		1		l as dot defect if defe			
		5. 3 Th	e distanc	e between two dot d	lefect ≧5 mm.		



### ◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion				
		6. 1 Round type ( Non-display or display) :				
		Dimension	Acceptance	(Q'ty)		
	Black or white	(diameter ÷ Φ)	A area	B area		
	dot v scratch v	$\Phi \le 0.15$	Ignore			
	contamination	$0.15 < \Phi \leq 0.20$	2			
	Round type	$0.20 < \Phi \leq 0.30$	2	Ignore		
	→ <u>x</u>	$\Phi > 0.30$	0			
06	Y Y	Total	3		Minor	
	$\Phi = (x+y)/2$	6. 2 Line type( Non-display or display) :			VIIIOI	
	Line type	Dimension	Acceptai	ace (Q'ty)		
	<b>∠</b> ↓	Length (L) Width (W)	A area	B area		
	<del>¯</del> ₩	W ≤ 0.0	03 Ignore			
	→ L I←	$L \le 5.0$ $0.03 < W \le 0.0$	05 3			
		W >0.	05 As round type	Ignore		
		Total	3			
		Dimension (diameter : Φ)	Acceptance			
			A area	B area		
07	Polarizer	Φ ≤ 0.20	Ignore		3.5	
01	Bubble	$0.20 < \Phi \leq 0.50$	3	Ignore	Minor	
		$\Phi > 0.50$	0	Ignore		
		Total	3			



### ◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion		Level
		Z : The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length	
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	nck between panels:	
		Y Z	Z Y	
08	The crack of glass	SP Y [OK]	SP [NG]	Minor
		Seal width Z	Y	
		X Y	Z	
		≤ a Crack can't enter viewing area	≤1/2 t	
		≤ a Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	
4				



# ◆Specification For TFT-LCD Module Less Than 3.5″:

NO	Item	Criterion (	Level
		Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  8. 1. 2 Corner crack:	
		$X$ $Y$ $Z$ $\leq 1/5 \text{ a} \qquad \begin{array}{c} \text{Crack can't enter} \\ \text{viewing area} \end{array} \qquad Z \leq 1/2 \text{ t}$	
00		$\leq 1/5$ a Crack can't exceed the half of SP width. $1/2$ t $<$ Z $\leq 2$ t	
08	The crack of glass		Minor
		8.2 Protrusion over terminal: 8.2.1 Chip on electrode pad:	
		W.Y. X. Y. Z. X.	
		X	
		X Y Z	
		Front $\leq a$ $\leq 1/2  \mathrm{W}$ $\leq t$	
		Back $\leq$ a $\leq$ W $\leq$ 1/2 t	



### ◆Specification For TFT-LCD Module Less Than 3, 5":

NO Item Criterion	Level
Symbols:  X: The length of crack Z: The thickness of crack T: The thickness of glass  8. 2. 2 Non-conductive portion:  X: The crack of glass  O If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electron terminal specifications.  8. 2. 3 Glass remain:  X: The width of crack. W: terminal length a: LCD side length  X: Y: The width of crack. W: terminal length a: LCD side length  Symbols:  X: The thickness of glass a: LCD side length  A: LCD side length  A: LCD side length  Symbols:  X: Y: The width of crack. W: terminal length a: LCD side length  Symbols:  X: Y: The width of crack. W: terminal length a: LCD side length  Symbols:  X: Y Z  Symbols:  X: Y Z  Symbols: X: The thickness of glass a: LCD side length	Minor



## ◆Specification For TFT-LCD Module Less Than 3, 5":

NO	Item	Criterion	Level
		9. 1 Backlight can't work normally.	Major
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	General appearance	10. 1 Pin type \quantity \quantity \dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
10		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10.5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is ≤1.5 mm.	Minor



# 4. RELIABILITY TEST

# **4.1 Reliability Test Condition**

			,		
NO.	TEST ITEM	TEST CONDITION			
1 1	<b>High Temperature</b>	<b>Keep in +80 ±2°</b> C 96 hrs			
	Storage Test	Surrounding temperature, then st	orage at normal condition 4hrs.		
2	Low Temperature	Keep in -30 ±2°C 96 hrs			
	Storage Test	Surrounding temperature, then st			
	High Temperature /	Keep in +60 °C / 90% R.H durat			
3	High Humidity Storage Test	Surrounding temperature, then st	orage at normal condition 4hrs.		
	Storage Test	(Excluding the polarizer)	.00°C .05°C		
			$\rightarrow$ +80°C $\rightarrow$ +25°C		
4	Temperature Cycling	(30mins) (5mins) <b>◆</b>			
	Storage Test		Cycle		
		Surrounding temperature, then st	orage at normal condition 4hrs.		
	ESD Test	Air Discharge:	Contact Discharge:		
		Apply 2 KV with 5 times	Apply 250 V with 5 times		
		Discharge for each polarity +/-	discharge for each polarity +/-		
		1. Temperature ambiance : 15°C ~35°C			
5		2. Humidity relative: 30%~60%			
		3. Energy Storage Capacitance(Cs+Cd): 150pF±10%			
		4. Discharge Resistance(Rd): 330 Ω±10%			
		5. Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec)			
			· ·		
		(Tolerance if the output voltage indication: ±5%)			
	Vibration Test	1. Sine wave 10 55 Hz frequen	= '		
6	(Packaged)	2. The amplitude of vibration :1.5 mm			
		3. Each direction (X · Y · Z) du	ration for 2 Hrs		
		Packing Weight (Kg	y) Drop Height (cm)		
		0 ~ 45.4	122		
	<b>Drop Test</b>	45.4 ~ 90.8	76		
7	(Packaged)	90.8 ~ 454	61		
		Over 454	46		
		Drop Direction: **1 corner / 3 ed	ges / 6 sides each 1time		



#### 5. PRECAUTION RELATING PRODUCT HANDLING

#### **5.1 SAFETY**

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

#### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}$ C  $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

#### **5.4 TERMS OF WARRANTY**

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

